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**Requirements for load ports of 300mm semiconductor
equipment**

300mm半导体设备装载端口要求

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Foreword

This document is in accordance with the provisions of GB/T 1.1-2020 "Guidelines for standardization work Part 1: Structure and drafting rules for standardization documents" Drafting is required.

Please note that some of the contents of this document may involve patents. The issuing organization of this document does not assume the responsibility for identifying patents.

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300 mm Semiconductor Equipment Loadport Requirements

1 Scope

This document specifies the dimensional requirements for the loading port of 300 mm wafer semiconductor equipment, mainly including the physical and chemical connection between the semiconductor equipment and the production line. Management interface.

This document is applicable to the field of semiconductor equipment design and manufacturing.

2 Normative references

This document has no normative references.

3 Terms and definitions

The following terms and definitions apply to this document.

3.1 Cassette

An open structure that holds one or more wafers.

3.2 Loading face plane

The physical vertical distance from the center of mass of the rack or wafer carrier that is farthest from the center of mass of the wafer carrier on the side (or sides) of the equipment where loading is performed. Straight plane.

3.3 load port

The interface position of the wafer carrier on the equipment.

3.4 Tilt

In order to keep the wafers aligned or prevent them from slipping out, the angles designed in the standard horizontal or vertical directions of the wafer rack or wafer carrier are Offset.

Note. The standard horizontal direction refers to the direction perpendicular to the loading surface.

3.5 Wafer carrier

Wafer racks, front-opening cassettes, SMIF (standard mechanical interface) cassettes, wafer boats and other carriers for storing wafers.